

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- White SMD package, silicone resin.
- Low thermal resistance.
- Compatible with IR-reflow processes.
- ESD protection.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 2a.
- · RoHS compliant.

3.5x3.5 mm SMD CHIP LED LAMP

Part Number: KA-3535SELZ4S Hyper Orange

Description

The Hyper Orange device is made with TS AlGaInP light emitting diode.

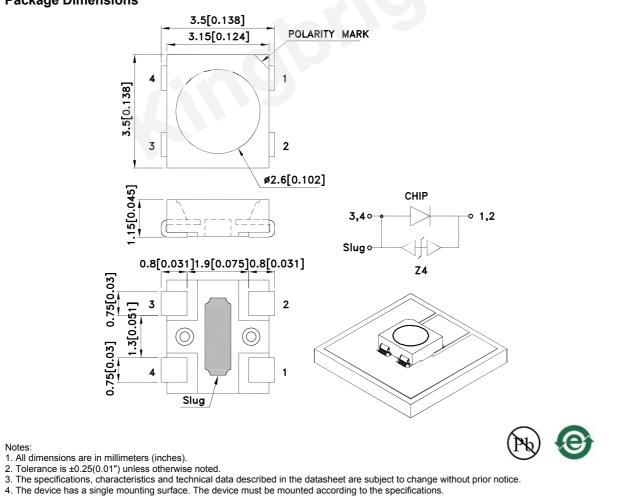
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Applications

- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- Commercial and residential lighting.
- Automotive interior lighting.



SPEC NO: DSAM0798 **APPROVED: WYNEC**

REV NO: V.4B CHECKED: Allen Liu DATE: MAR/29/2013 DRAWN: F.Cui

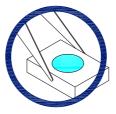
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Package Dimensions

Handling Precautions

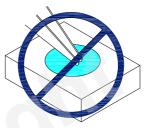
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

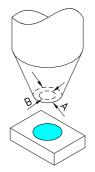




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Detailed application notes are listed on our website. http://www.kingbright.com/application_notes

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Selection Guide

| Part No. | Dice | Lens Type | lv (cd) [2] @ 150mA | | Φν (lm) [2] @ 150mA | | Viewing Angle [1] |
|---------------|------------------------|-------------|------------------------|------|------------------------|------|----------------------|
| | | | Min. | Тур. | Min. | Тур. | 2 0 1/2 |
| KA-3535SELZ4S | Hyper Orange (AlGaInP) | Water Clear | 2.7 | 3.6 | 8.6 | 11 | 120 ° |

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3.LEDs are binned according to their luminous flux. 4.Luminous intensity/ luminous Flux value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

| Parameter | Symbol | Value | Unit |
|---|---------|------------|------|
| Power Dissipation | PD | 510 | mW |
| Junction Temperature [1] | TJ | 130 | °C |
| Operating Temperature | Тор | -40 To +85 | °C |
| Storage Temperature | Tstg | -40 To +85 | °C |
| DC Forward Current [1] | lF | 150 | mA |
| Reverse Voltage | VR | 5 | V |
| Peak Forward Current [2] | lfм | 270 | mA |
| Thermal Resistance [1] (Junction/ambient) | Rth j-a | 240 | °C/W |
| Thermal Resistance [1] (Junction/solder point) | Rth j-S | 100 | °C/W |
| Electrostatic Discharge Threshold (HBM) | | 8000 | V |

Notes:

1.Results from mounting on PC board FR4(pad size ≥ 70mm²), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

2.1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at TA=25°C

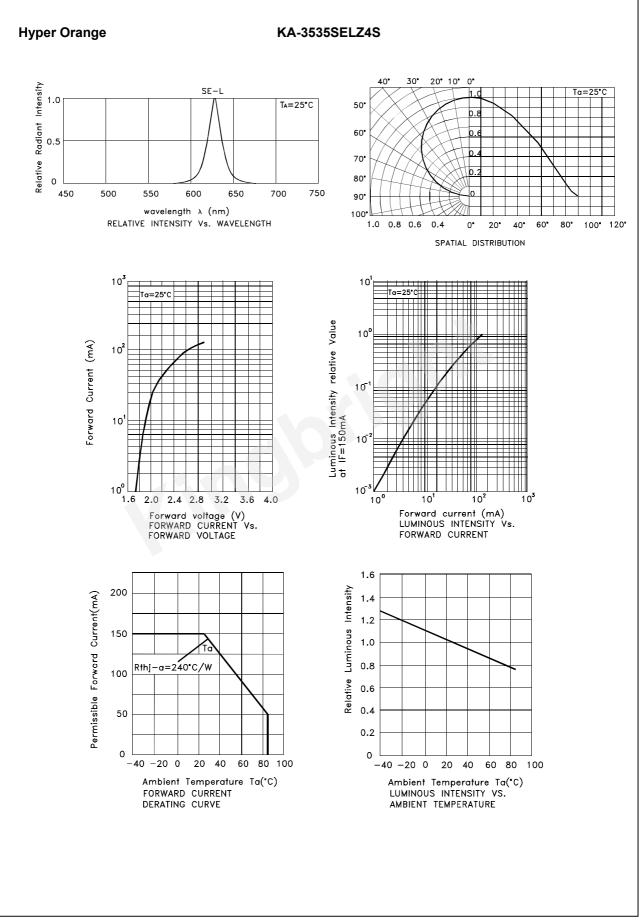
| Parameter | Symbol | Value | Unit |
|--|-------------------|-------|--------|
| Wavelength at peak emission IF=150mA [Typ.] | λ peak | 630 | nm |
| Dominant Wavelength IF=150mA [Typ.] | λ dom [1] | 618 | nm |
| Spectral Line Half-width IF=150mA [Typ.] | Δλ | 20 | nm |
| Forward Voltage IF=150mA [Min.] | 150mA [Min.] | | |
| Forward Voltage IF=150mA [Typ.] | VF [2] | 2.9 | V |
| Forward Voltage IF=150mA [Max.] | | 3.4 | |
| Allowable Reverse Current [Max.] | lr | 85 | mA |
| Temperature coefficient of λ peak Ir=150mA, -10 $^\circ$ C \leq T \leq 100 $^\circ$ C $% \label{eq:result}$ [Typ.] | TC λ peak | 0.11 | nm/° C |
| Temperature coefficient of λ dom IF=150mA, -10 ° C \leq T \leq 100 ° C [Typ.] | $TC \lambda$ dom | 0.09 | nm/° C |
| Temperature coefficient of VF IF=150mA, -10 $^\circ$ C \leq T \leq 100 $^\circ$ C [Typ.] | TCv | -3.6 | mV/° C |

Notes:

1.Wavelength: +/-1nm.

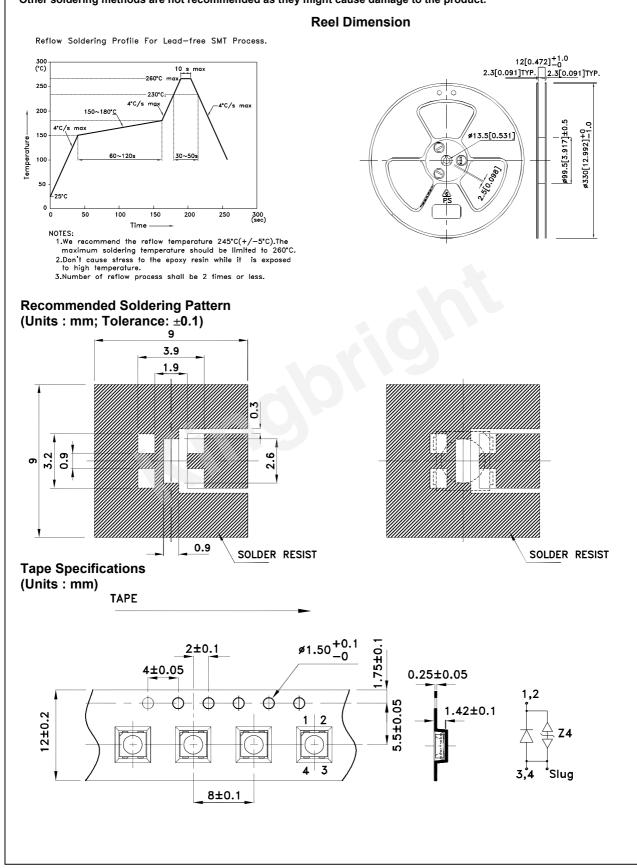
2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.



KA-3535SELZ4S

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.



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